LCD驱动器

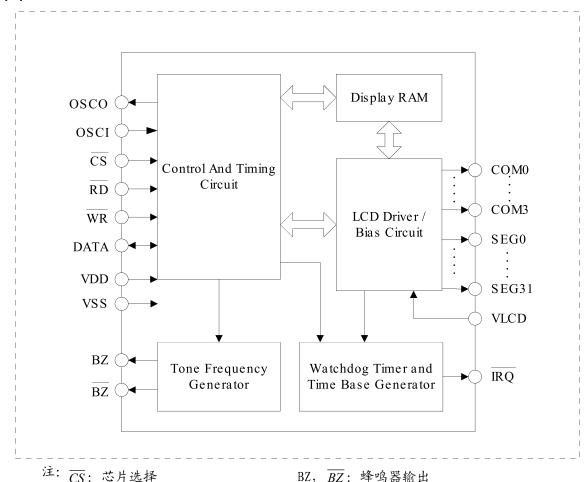
器件概述

HT1621 是一种128 点阵式存储映射多功能LCD驱动电路。 HT1621 的S/W 结构特点,使它适合点阵式LCD 显示,包括LCD模块和显示子系统,HT1621还具有节电功能。其主要特点如下:

- 工作电压: 2.4V~5.2V
- 内部 256KHz RC振荡器
- 外部 32KHz晶振或 256KHz频率输入
- 可选择 1/2或 1/3偏置和 1/2 1/3或 1/4占空比 LCD 显示
- 蜂鸣器驱动信号频率可选择 2KHz或 4KHz
- 内部时基发生器和 WDT 看门狗定时器
- 数据模式和命令模式指令
- VLCD 引脚用来调整 LCD 工作电压
- 芯片尺寸: 1690×1910(m×m)
- 芯片衬底接 VDD
- 封装形式: SSOP-48L / SOP-28L / SOP-24L / QFP-44L

- 内部时基频率源
- 具有关机指令可减少功耗
- 内部时基或 WDT 溢出输出
- 八个时基/WDT时钟的时钟源
- 32×4 LCD 驱动器
- 内部 32× 4bit显示 RAM
- 四路串行接口
- 内部 LCD 驱动频率源
- 可用指令控制操作
- R/W地址自动累加
- 三种数据访问模式

功能框图



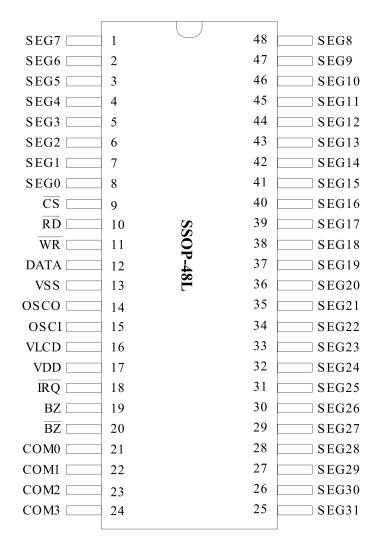
注: CS: 芯片选择

WR, RD, DATA: 串行接口

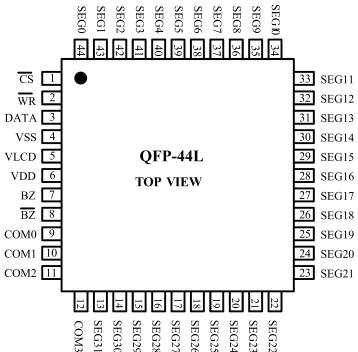
COM0~COM3, SEG0~SEG31: LCD输出

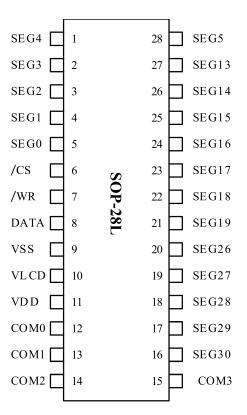
IRO: 时间基准或 WDT 溢出输出

引脚排列图



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SEG17	1		24	SEG18
SEG16	2		23	SEG19
SEG15	3		22	SEG20
SEG14	4		21	SEG21
SEG13	5	Š	20	SEG22
SEG12	6	SOP-24I	19	COM3
SEG11	7	24L	18	COM2
SEG10	8		17	COM1
SEG9	9		16	COM0
/cs 🗆	10		15	VDD
/WR	11		14	VL CD
DATA 🗌	12		13	VSS
l				

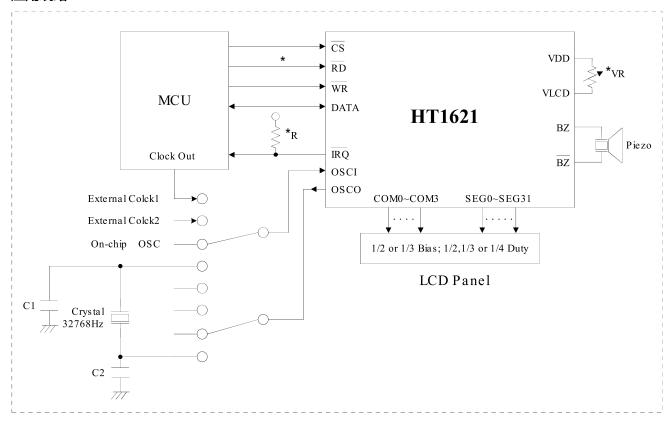






典型应用线路

应用线路



使用说明:

IRO 和 RD 引脚的连接视主控制器的要求而定。

VLCD 引脚的电压必须低于 VDD。

调节 VR 以适应 LCD 显示器, VDD=5V, VLCD=4V VR=15K ±20%。

调节 R (外接上拉电阻) 以适应用户的基准时钟。

为了获得最佳性能,需要增加两个 2 个额外的负载电容 C1、C2, 电容值的大小影响晶振的精度,建议按下表进行取值。

C1、C2 电容取值说明:

晶振误差	电容值 (C1、C2)		
±ppm	0~10P		
10~20ppm	10~20P		



订购信息

部品编码	描述	工作温度	封装结构	器件印字	包装数量
HT1621AS48	Vin: 2.4~5.2V 256KHz RC I _{STB} : 5.0uA 32*4 LCD Driver 32*4bit RAM	-25 ~ 70°C	SSOP-48L	1621A ** **	30PCS/Tube 2400PCS/Reel
HT1621BS28			SOP-28L	1621B ** **	25PCS/Tube 2000PCS/Reel
HT1621CS24			SOP-24L	1621C ** **	60PCS/Tube 9600PCS/Reel
HT1621DQ44			QFP-44L	1621D ** **	96PCS/Plate 960PCS/Reel

Note:

- > HT1621 devices are Pb-free and RoHS compliant.
- The surface prints of our semiconductor devices are subject to change during the production process and do not involve changes in electrical parameters, and we will not separately state the notice.
- > If you have any other custom purchase needs, please contact our sales department.



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.











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